



DT1446-04S

#### 4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

## **Product Summary**

| V <sub>BR (min)</sub> | I <sub>PP (max)</sub> | C <sub>T (typ)</sub> |
|-----------------------|-----------------------|----------------------|
| 6V                    | 4.7A                  | 0.55pF               |

#### **Description**

The DT1446-04S is a high performance device suitable for protecting four high speed I/Os and one  $V_{CC}$ . These devices are assembled in SOT363 package. They have high ESD surge capability and low capacitance.

#### **Applications**

Typically Used for High Speed Ports such as:

- USB 2.0
- IEEE1394
- HDMI
- Laptop and Personal Computers
- Flat Panel Displays
- Video Graphics Displays
- SIM Ports

**SOT363** 



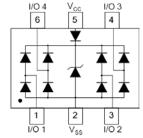
Top View

#### **Features**

- IEC 61000-4-2 (ESD): Air ±19kV, Contact ±16kV
- Low Channel Input Capacitance of 0.55pF Max
- ESD Protection for four I/Os and one V<sub>CC</sub>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020 (Lead Free Plating).
   Solderable per MIL-STD-202, Method 208<sup>3</sup>
- Weight: 0.006 grams (approximate)



**Device Schematic** 

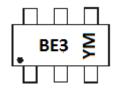
#### **Ordering Information** (Note 4)

| Product      | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|--------------|------------|---------|--------------------|-----------------|-------------------|
| DT1446-04S-7 | Standard   | BE3     | 7                  | 8               | 3,000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**



BE3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

| Date Code Rey |      |      |      |      |      |      |
|---------------|------|------|------|------|------|------|
| Year          | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 |
| Code          | Α    | В    | С    | D    | E    | F    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | 0   | N   | D   |



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                                    | Symbol               | Value | Unit | Conditions   |
|---|----------------------|-------|------|--|
| Peak Pulse Current ,per IEC 61000-4-5             | I <sub>PP_I/O</sub>  | 4.7   | Α    | I/O to V <sub>SS</sub> , 8/20µs                        |
| Operating Voltage (DC)                            | $V_{DC}$             | 6     | V    | V <sub>CC</sub> to V <sub>SS</sub>                     |
| ESD Protection – Contact Discharge                | V <sub>ESD_I/O</sub> | ±16   | kV   | I/O to V <sub>SS</sub> , per IEC 61000-4-2             |
| LSD Flotection - Contact Discharge                | $V_{ESD}V_{CC}$      | ±30   | kV   | V <sub>CC</sub> to V <sub>SS</sub> , per IEC 61000-4-2 |
| ESD Protection – Air Discharge, per IEC 61000-4-2 | V <sub>ESD_I/O</sub> | ±19   | kV   | I/O to V <sub>SS</sub> , per IEC 61000-4-2             |
| L3D Flotection – All Discharge, per IEC 61000-4-2 | $V_{ESD}V_{CC}$      | ±30   | kV   | V <sub>CC</sub> to V <sub>SS</sub> , per IEC 61000-4-2 |

## **Thermal Characteristics**

| Characteristic   | Symbol                            | Value      | Unit |
|--|-----------------------------------|------------|------|
| Power Dissipation Typical (Note 5)                       | P <sub>D</sub>                    | 200        | mW   |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | R <sub>θJA</sub>                  | 625        | °C/W |
| Operating and Storage Temperature Range                  | T <sub>J</sub> , T <sub>STG</sub> | -55 to 150 | °C   |

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                            | Symbol  | Min | Тур  | Max  | Unit | Test Conditions  |
|---|---|-----|------|------|------|--|
| Reverse Working Voltage                   | VRWM  | _   | _    | 5.0  | V    | V <sub>CC</sub> to V <sub>SS</sub>   |
| Reverse Current (Note 6)                  | I <sub>R(</sub> V <sub>CC to</sub> V <sub>SS)</sub> | _   | _    | 5.0  | μA   | $V_R = V_{RWM} = 5V$ , $V_{CC}$ to $V_{SS}$  |
| Reverse Current (Note 6)                  | I <sub>R(IO to</sub> V <sub>SS)</sub>               | _   | _    | 1.0  | μA   | $V_R = V_{RWM} = 5V$ , any I/O to $V_{SS}$   |
| Reverse Breakdown Voltage                 | V <sub>BR</sub>                                     | 6.0 | _    | 9.0  | V    | I <sub>R</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub>   |
| Forward Clamping Voltage                  | V <sub>F</sub>                                      |     | 0.8  | 1.0  | V    | I <sub>F</sub> = 15mA, V <sub>SS</sub> to V <sub>CC</sub>  |
| Reverse Clamping Voltage (Note 7)         | V <sub>C_I/O</sub>                                  | _   | 8.5  | _    | V    | I <sub>PP</sub> =4.7A, I/O to V <sub>SS</sub> , 8/20μs   |
| ESD Clamping Valtage                      | Vesd_Vcc  | _   | 10   | _    | V    | TLP, 20A, tp = 100ns, V <sub>CC</sub> to V <sub>SS</sub>   |
| ESD Clamping Voltage                      | Vesd_i/o  | _   | 12   | _    | V    | TLP, 20A, tp = 100ns, I/O to V <sub>SS</sub>   |
| Dynamia Resistance                        | R <sub>DIF_</sub> V <sub>CC</sub>                   | _   | 0.14 | _    | Ω    | TLP, 20A, tp = 100ns, V <sub>CC</sub> to V <sub>SS</sub>   |
| Dynamic Resistance                        | R <sub>DIF_I/O</sub>                                | _   | 0.3  | _    | Ω    | TLP, 20A, tp = 100ns, I/O to $V_{SS}$  |
| Channel Input Capacitance                 | C <sub>I/O to</sub> V <sub>SS</sub>                 | _   | 0.55 | 0.65 | pF   | $V_R = 2.5V, V_{CC} = 5V, f = 1MHz$  |
| Channel Input Capacitance                 | C <sub>I/O to</sub> V <sub>SS</sub>                 | _   | 0.65 | _    | pF   | V <sub>R</sub> = 2.5V, V <sub>CC</sub> = floating, f = 1MHz  |
| Variation of Channel Input<br>Capacitance | C <sub>I/OMAX</sub> -C <sub>I/OMIN</sub>            | _   | 0.03 | _    | pF   | $V_{CC} = 5V$ , $V_{SS} = 0V$ , $I/O = 2.5V$ , $f = 1MHz$ , $T = +25^{\circ}C$ , $C_{I/OMAX} - C_{I/OMIN}$ |
| Variation of Channel Input<br>Capacitance | C <sub>I/OMAX</sub> -C <sub>I/OMIN</sub>            | _   | 0.05 | _    | pF   | $V_{CC}$ = floating , $V_{SS}$ = 0V, I/O = 2.5V,<br>f = 1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$      |

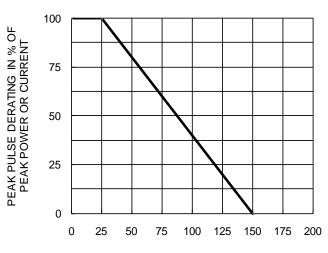
Notes:

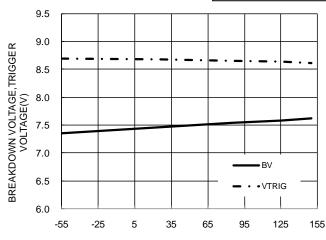
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

  6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an  $8x20\mu s$  peak pulse current ( $I_{pp}$ ) waveform.



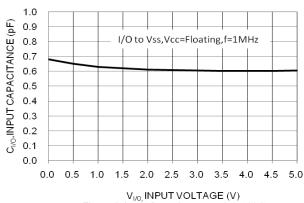
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T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Figure 1. Pulse Derating Curve

T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Figure 2. BV, Trigger Voltage vs. Ambient Temperature



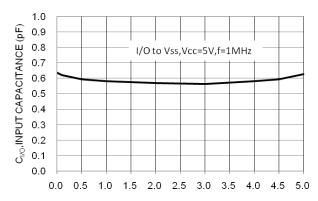
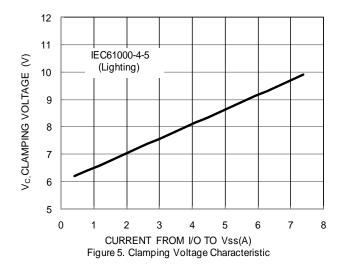


Figure 3. Input Capacitance vs. Input Voltage

V<sub>I/O,</sub> INPUT VOLTAGE (V) Figure 4. Input Capacitance vs. Input Voltage



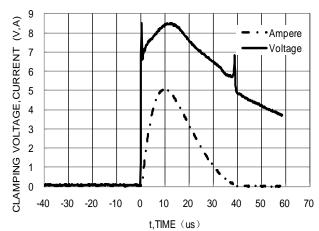


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us,I/O to Vss)

July 2014



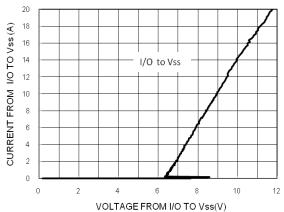
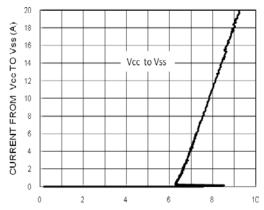


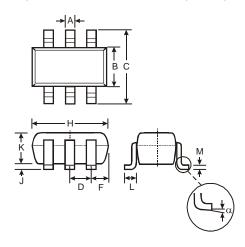
Figure 7. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage



VOLTAGE FROM Vcc TO Vss(V)
Figure 8. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage

# **Package Outline Dimensions**

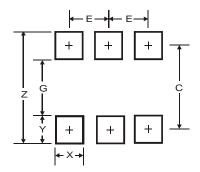
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SOT363               |      |         |       |  |  |  |  |
|----------------------|------|---------|-------|--|--|--|--|
| Dim                  | Min  | Max     | Тур   |  |  |  |  |
| Α                    | 0.10 | 0.30    | 0.25  |  |  |  |  |
| В                    | 1.15 | 1.35    | 1.30  |  |  |  |  |
| ပ                    | 2.00 | 2.20    | 2.10  |  |  |  |  |
| D                    |      | 0.65 Ty | p     |  |  |  |  |
| F                    | 0.40 | 0.45    | 0.425 |  |  |  |  |
| Н                    | 1.80 | 2.20    | 2.15  |  |  |  |  |
| J                    | 0    | 0.10    | 0.05  |  |  |  |  |
| K                    | 0.90 | 1.00    | 1.00  |  |  |  |  |
| L                    | 0.25 | 0.40    | 0.30  |  |  |  |  |
| М                    | 0.10 | 0.22    | 0.11  |  |  |  |  |
| α                    | 0°   | 8°      | -     |  |  |  |  |
| All Dimensions in mm |      |         |       |  |  |  |  |

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 2.5           |
| G          | 1.3           |
| Х          | 0.42          |
| Y          | 0.6           |
| С          | 1.9           |
| E          | 0.65          |



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